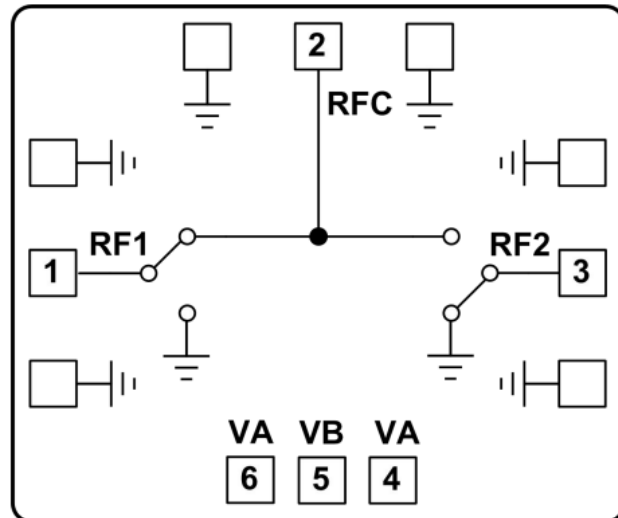


Features

- SPDT Reflective design
- Isolation: 35dB@18GHz
- Insertion Loss: 1.5dB@18GHz
- Input P-0.1: 37dBm@ 18GHz
- Input P-0.3: 39dBm@ 18GHz
- Switching Time: 20ns
- Input/Output: 50 Ohm matched
- Die Size: 1.40x0.83x 0.10 mm

Typical Applications

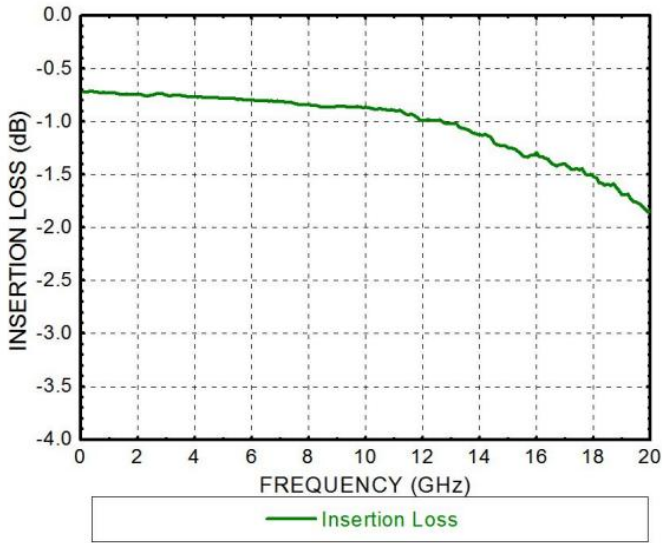
- TTL compatible driver included
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

Functional Block Diagram

Electrical Specifications
TA = +25°C, VCTL=0/-40V

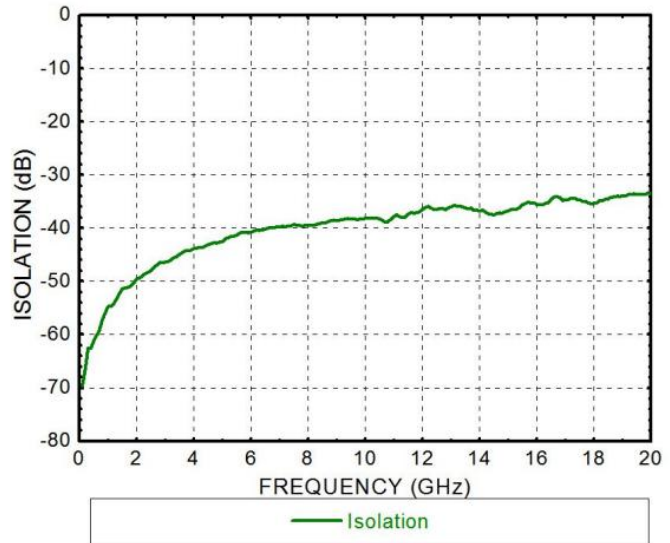
Parameters	Min.	Typ.	Max.	Units
Frequency		0.5-18		GHz
Insertion Loss@6GHz		0.8		dB
Insertion Loss@18GHz		1.5		dB
On-state Return Loss(RFC)		15		dB
On-state Return Loss(RF1/RF2)		15		dB
Off-state Return Loss		2		dB
Off-state Isolation@6GHz		41		dB
Off-state Isolation@18GHz		35		dB
Input power 0.3dB Compression@18GHz		39		dBm
Switching Time		20		ns



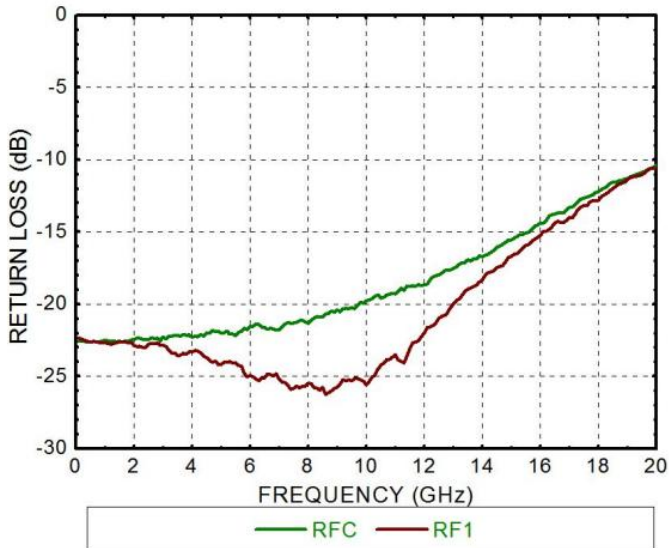
Insertion Loss



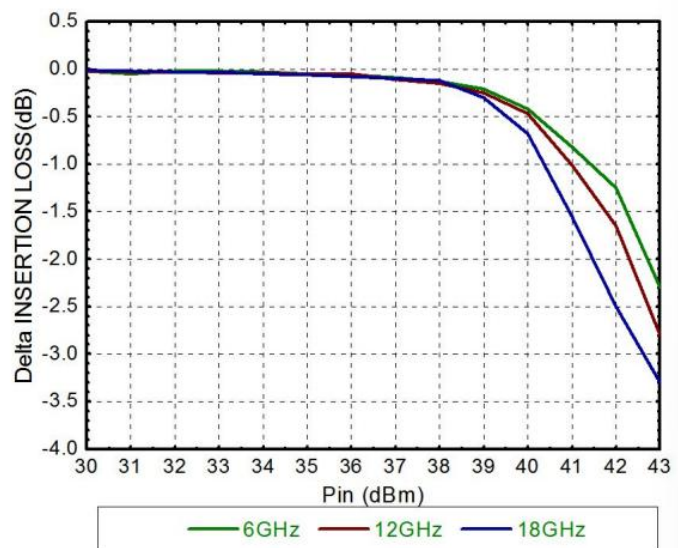
Isolation



Return Loss (ON State)

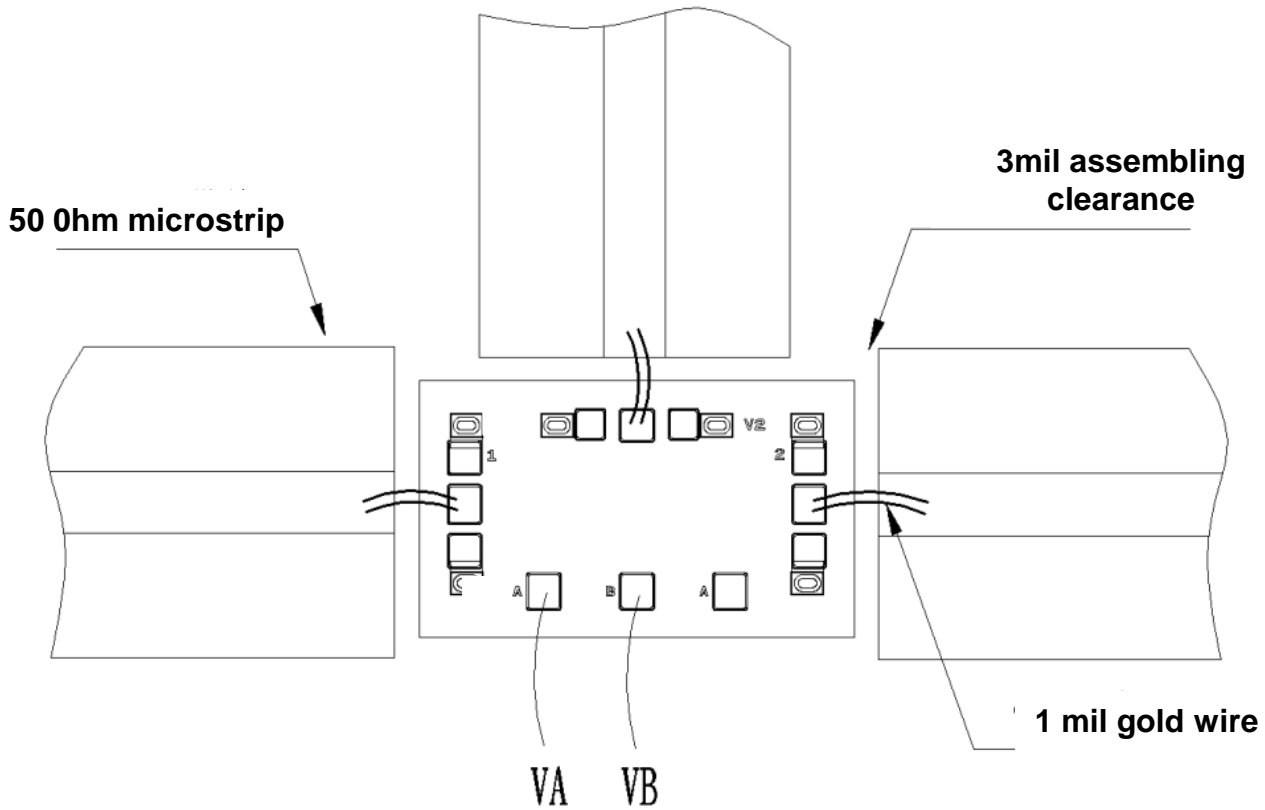


Insertion Loss Compression vs Input Power (Normalized)





Assembly Drawing



Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. Control voltage: -50V
2. Control current: 2mA
3. Maximum input power: +42dBm
(Continuous wave, 50 Ω , withstands for 20 minutes)
4. Storage temperature: -65°C to +150°C
5. Operating temperature: -55°C to +85°C